## **Electronic Supplementary Information**

# Enhanced thermoelectric performance in ternary spinel Cu<sub>4</sub>Mn<sub>2</sub>Te<sub>4</sub> *via* synergistic effect of tellurium-deficiency and chlorine-doping

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### **Experimental methods**

#### Sample preparation and Property characterization

All of the samples were prepared by solid-state reactions. The weighing manipulation was carried out in an argon-filled glove-box (moisture and oxygen levels less than 0.1 ppm). An approximately total 4 g of reactants (Cu, 5N; Mn, 5N; Te, 5N; MnCl<sub>2</sub>, 3N, all purchased from Sinopharm Chemical Reagent Co., Ltd.) were mixed and loaded in carbon-coated silica tubes under a residual pressure of  $\sim 10^{-3}$  Pa. The samples were placed into a temperature-controlled muffle furnace, slowly heated to 773 K in 50 h (to aid the volatilizations of raw materials), kept at this temperature for 1 day, and then heated to 1223 K in 30 h, subsequently, annealed at this temperature for 96h. After the furnace cooled to room temperature, the obtained ingots were taken out from the quartz and hand-milled into powders for follow-up hot pressed under 70 MPa at 973 K for 60 minutes in a graphite-steel mold with a 16 mm internal diameter. The obtained pellets were then cut into rectangular pieces of  $\sim 10 \times 3 \times 2$  mm for electrical

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transport measurements, while coins of  $\Phi \sim 10$  mm and thickness of  $\sim 2$  mm were used for thermal diffusivity measurements. Seebeck coefficient and electrical resistivity were measured simultaneously in Ultravac ZEM-3 under a helium atmosphere. The thermal diffusivity (D) was measured through laser flash method with Netzsch LFA-457 system. The heat capacity ( $C_p$ ) was indirectly derived using a representative sample (Pyroceram9606). The total thermal conductivity was calculated via  $k = D \cdot C_p \cdot d$ , where d was the measured density, which was determined using the dimensions and mass of the sample and then reconfirmed by measurements using Archimedes' principle on a home-built device. All the transport property measurements were performed in the temperature range of 300-773 K. Thermal gravimetric analysis (TGA) scan was measured on a NETZSCH STA 449C simultaneous analyzer under a constant flow of nitrogen gas. Differential scanning calorimetry (DSC) cycling curves were measured by the NETZSCH DTA 404PC with a heating/cooling rate of 5 K/min between 300 and 973 K under an atmosphere of N2. The powder X-ray diffraction (XRD) patterns were taken at room temperature on a Rigaku DMAX 2500 powder X-ray diffractometer by using Cu K<sub>a</sub> radiation.



Figure S1. (a) TGA and (b) DSC diagrams of polycrystalline Cu<sub>4</sub>Mn<sub>2</sub>Te<sub>4</sub> sample.



Figure S2. Powder XRD patterns of polycrystalline Cu<sub>4</sub>Mn<sub>2</sub>Te<sub>4</sub> sample before and

after hot-pressing.



**Figure S3**. Temperature dependence of the electrical transport properties of polycrystalline Cu<sub>4</sub>Mn<sub>2</sub>Te<sub>4</sub> sample using hot-pressing: (a) electrical conductivity ( $\sigma$ ), (b) Seebeck coefficient (*S*), and (c) power factor (*PF* = *S*<sup>2</sup> $\sigma$ ). The data from ref.31 is also shown for comparison.



**Figure S4.** Temperature dependence of (a) Lorenz number (*L*) and electronic thermal conductivity ( $k_e$ ) for polycrystalline Cu<sub>4+x</sub>Mn<sub>2</sub>Te<sub>4- $\delta$ -y</sub>Cl<sub>y</sub> samples (x = 0/0.01/0.02,  $\delta$  = 0, y = 0; x = 0,  $\delta$  = 0.02/0.04, y = 0; x = 0,  $\delta$  = 0.04, y = 0.02/0.03/0.04).



**Figure S5**. (a) Electrical conductivity ( $\sigma$ ) and (b) Seebeck coefficient (*S*) as a function of the temperature for a hot-pressed polycrystalline sample of Cu<sub>4</sub>Mn<sub>2</sub>Te<sub>3.93</sub>Cl<sub>0.03</sub> during two thermal cycles.